

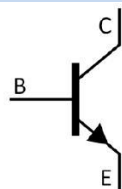
/ Descriptions

SOT-23                  NPN

/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



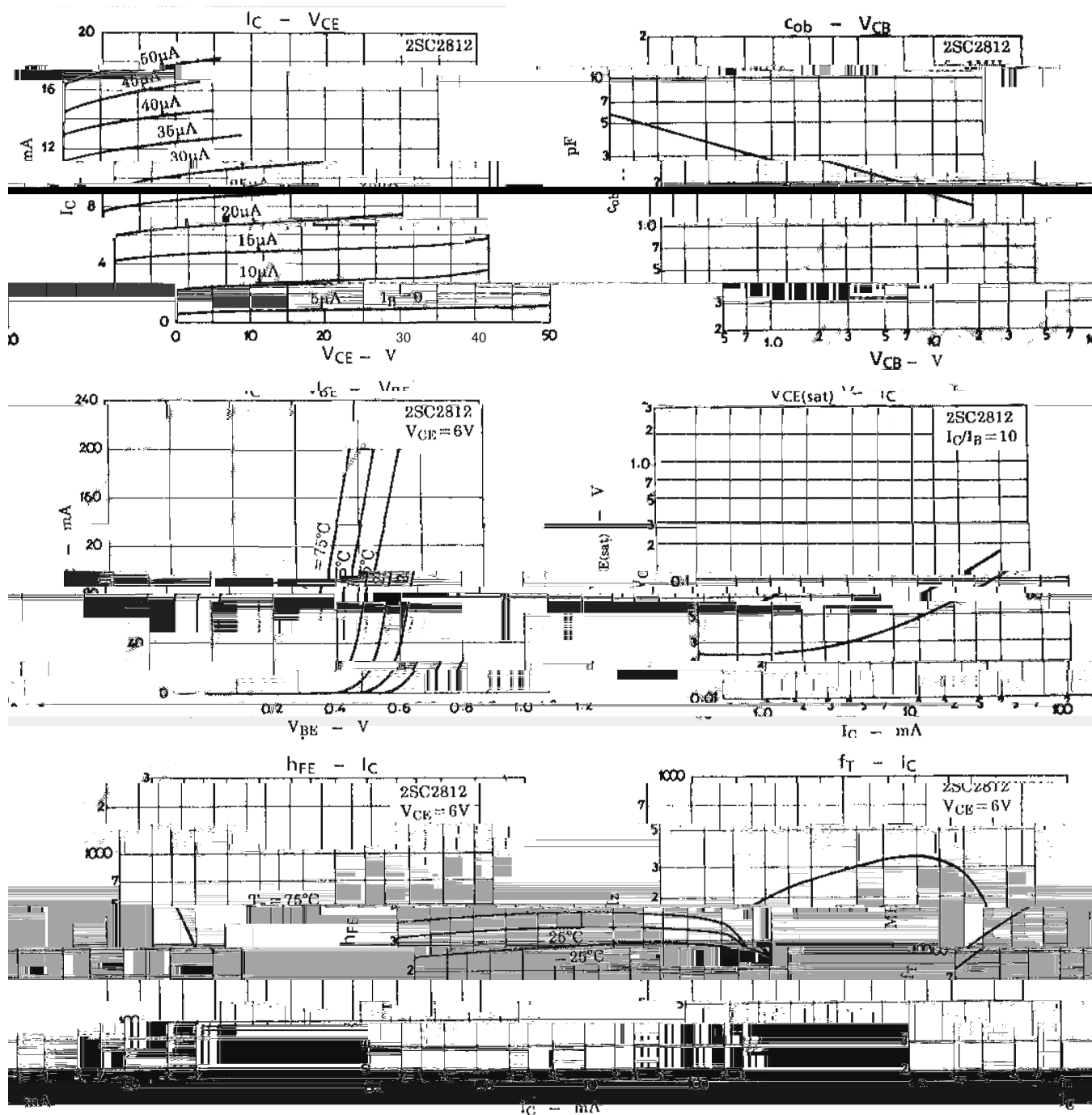
/  $h_{FE}$  Classifications & Marking

|  |  |  |  |  |
|--|--|--|--|--|
|  |  |  |  |  |
|  |  |  |  |  |
|  |  |  |  |  |

|  |  |  |  |
|--|--|--|--|
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |
|  |  |  |  |

|  |  |  |  |  |  |   |
|--|--|--|--|--|--|---|
|  |  |  |  |  |  |   |
|  |  |  |  |  |  | μ |
|  |  |  |  |  |  | μ |
|  |  |  |  |  |  |   |
|  |  |  |  |  |  |   |
|  |  |  |  |  |  |   |
|  |  |  |  |  |  |   |

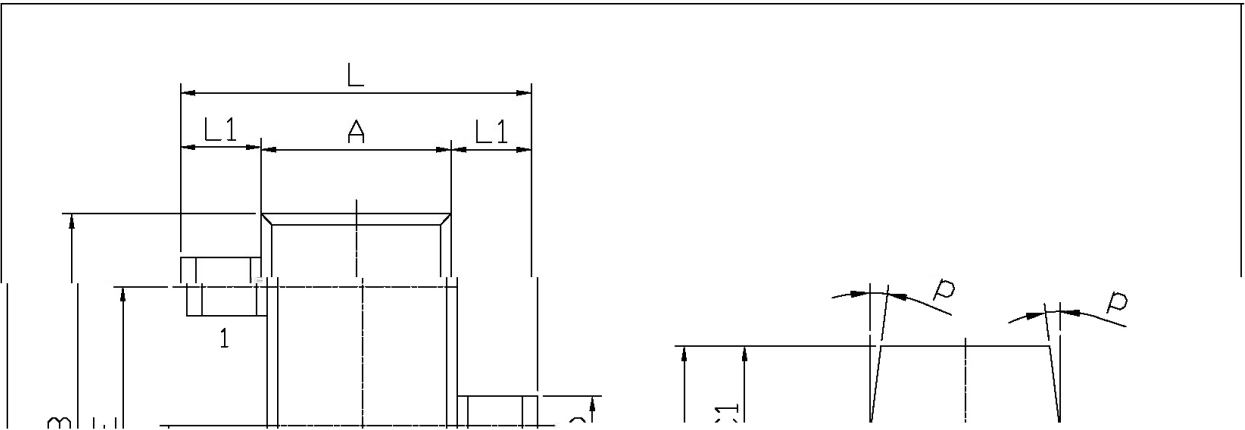
## / Electrical Characteristic Curve



/ Package Dimensions

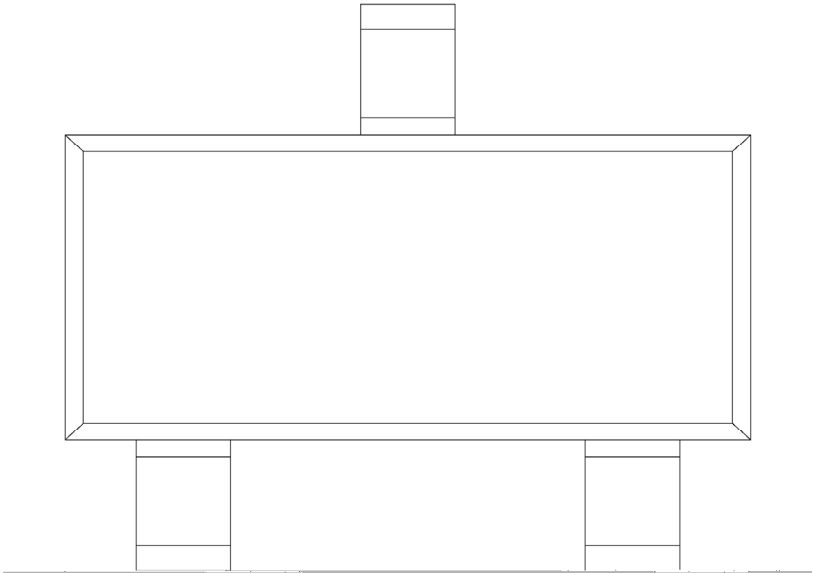
SOT-23

单位：mm



|    | MIN  | MAX  |    | MIN     | MAX  |
|----|------|------|----|---------|------|
| L  | 2.2  | 2.7  | C  | 1.30Max |      |
| L1 | 0.45 | 0.65 | C1 | 0.90    | 1.20 |
| A  | 1.15 | 1.50 | ∠  | 0.05    | 0.20 |
| B  | 2.70 | 3.10 | K  | 0       | 0.10 |
| E  | 1.70 | 2.10 | M  | 0.20MIN |      |
| E1 | 0.85 | 1.05 | P  | 7°      |      |
| b  | 0.35 | 0.55 |    |         |      |

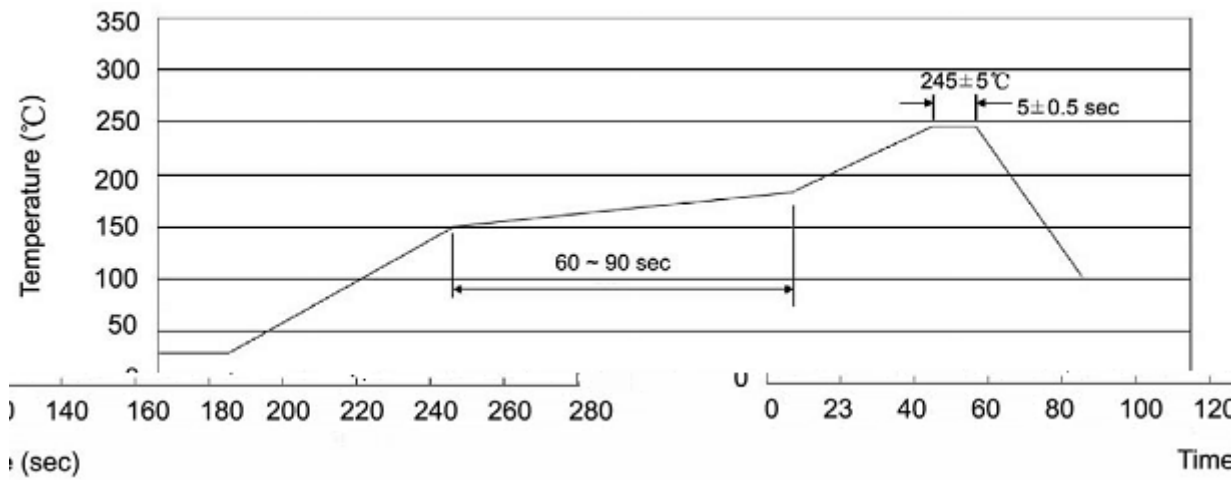
/ Marking Instructions



L  
4  
H

L  
4  
H

(     ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

| 封装形式 | 包装数量 |      |     |     |     | 包装尺寸 |   |   |
|------|------|------|-----|-----|-----|------|---|---|
|      | 只 卷盘 | 卷盘 盒 | 只 盒 | 盒 箱 | 只 箱 |      | 盒 | 箱 |